HALOGEN

FREE



N-Channel 100 V (D-S) MOSFET



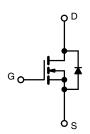
PRODUCT SUMMARY					
V _{DS} (V)	100				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.0292				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0330				
Q _g typ. (nC)	8.8				
I _D (A)	8.3				
Configuration	Single				

FEATURES

- TrenchFET® Gen IV power MOSFET
- Very low R_{DS} x Q_g figure-of-merit (FOM)
- Tuned for the lowest R_{DS} x Q_{oss} FOM
- · Logic level gate drive
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Synchronous rectification
- Primary side switch
- DC/DC converter
- · Motor drive switch
- LED driver
- · Load switch



N-Channel MOSFET

ORDERING INFORMATION	
Package	SO-8
Lead (Pb)-free and halogen-free	Si4056ADY-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V_{DS}	100		
Gate-source voltage		V_{GS}	± 20	V	
-	T _C = 25 °C		8.3		
0 " 15000	T _C = 70 °C	1 . [6.6	Ī	
Continuous drain current (T _J = 150 °C)	T _A = 25 °C	I _D	5.9 ^{b, c}		
	T _A = 70 °C	† †	4.7 b, c	A	
Pulsed drain current (t = 100 μs)		I _{DM}	40	7	
Continuous source-drain diode current	T _C = 25 °C	,	4.5	<u> </u>	
	T _A = 25 °C	l _S	2.3 ^{b, c}		
Single pulse avalanche current		I _{AS}	12	Ī	
Single pulse avalanche energy	L = 0.1 mH		7.2	mJ	
Maximum power dissipation	T _C = 25 °C		5.0		
	T _C = 70 °C	T _ [3.2	W	
	T _A = 25 °C	P _D	2.5 ^{b, c}		
	T _A = 70 °C	1	1.6 ^{b, c}	1	
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) c			260	1	

THERMAL RESISTANCE RATINGS							
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT			
Maximum junction-to-ambient ^b	t ≤ 10 s	R _{thJA}	43	50	°C/W		
Maximum junction-to-case (drain)	Steady state	R _{thJC}	19	25	C/VV		

Notes

- a. $T_C = 25 \,^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. Maximum under steady state conditions is 92 $^{\circ}\text{C/W}$

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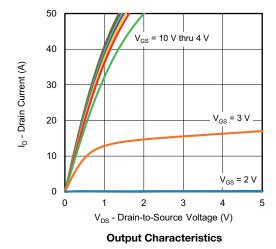
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static					•		
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	85	-	\/00	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-4.5	-	mV/°0	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	1	-	2.5	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	100	nA	
Zoro goto voltogo droin overent		V _{DS} = 100 V, V _{GS} = 0 V	-	-	1	μΑ	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15		
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	20	=	-	Α	
Drain-source on-state resistance ^a	В	V _{GS} = 10 V, I _D = 5.9 A	-	0.0243	0.0292	Ω	
Drain-Source on-State resistance "	R _{DS(on)}	V _{GS} = 4.5 V, I _D = 5.5 A	-	0.0277	0.0330		
Forward transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 10 A	-	49	-	S	
Dynamic ^b							
Input capacitance	C _{iss}		-	1330	-	pF	
Output capacitance	C _{oss}	$V_{DS} = 50 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	69	-		
Reverse transfer capacitance	C _{rss}		-	7.2	-		
Total gate charge	Qg	$V_{DS} = 50 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 10 \text{ A}$	-	19.2	29	nC	
			-	8.8	14		
Gate-source charge	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$	-	4.3	-		
Gate-drain charge	Q _{gd}		-	2.1	-		
Output charge	Q _{oss}	V _{DS} = 50 V, V _{GS} = 0 V	-	13.6	-		
Gate resistance	Rg	f = 1 MHz	0.3	0.87	1.5	Ω	
Turn-on delay time	t _{d(on)}		-	9	18		
Rise time	t _r	$V_{DD} = 50 \text{ V}, \text{ R}_L = 5 \Omega, \text{ I}_D \cong 10 \text{ A},$	-	6	12		
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	19	38		
Fall time	t _f		-	4	8		
Turn-on delay time	t _{d(on)}		-	14	28	ns	
Rise time	t _r	$V_{DD} = 50 \text{ V}, R_L = 5 \Omega, I_D \cong 10 \text{ A},$	-	8	16	1	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	15	30		
Fall time	t _f		-	5	10		
Drain-Source Body Diode Characteristi	cs						
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	35.4		
Pulse diode forward current	I _{SM}		-	-	40	A	
Body diode voltage	V_{SD}	$I_{S} = 5 \text{ A}, V_{GS} = 0 \text{ V}$	-	0.78	1.1	V	
Body diode reverse recovery time	t _{rr}		-	29	58	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	39	78	nC	
Reverse recovery fall time	t _a	$T_J = 25 ^{\circ}\text{C}$	-	25	-		
Reverse recovery rise time	t _b		-	4	-	ns	

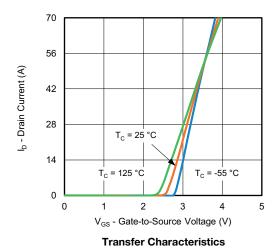
Notes

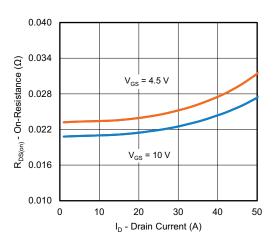
- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. Guaranteed by design, not subject to production testing

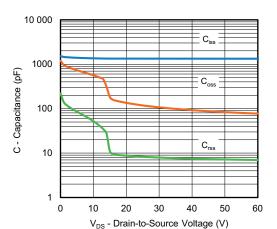
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.





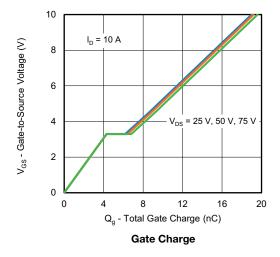


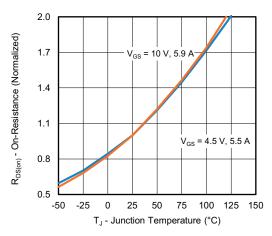




On-Resistance vs. Drain Current and Gate Voltage

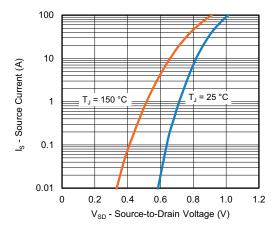




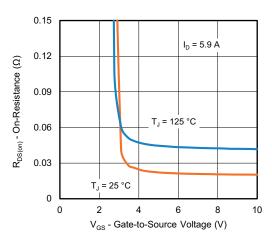


On-Resistance vs. Junction Temperature

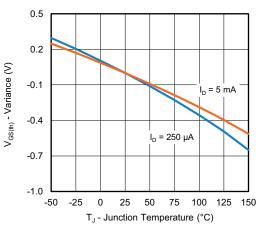




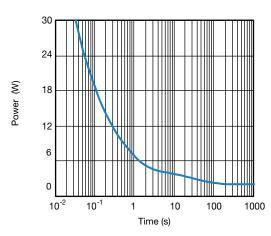
Source-Drain Diode Forward Voltage



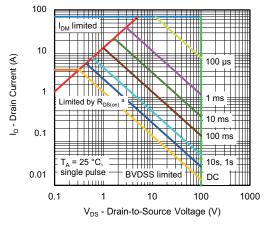
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage



Single Pulse Power, Junction-to-Ambient

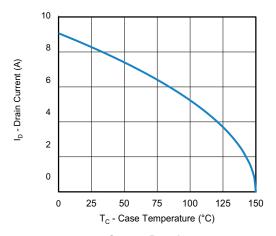


Safe Operating Area, Junction-to-Ambient

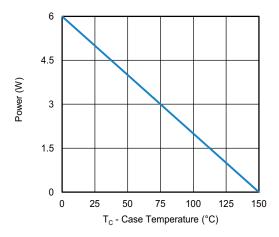
Note

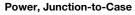
a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

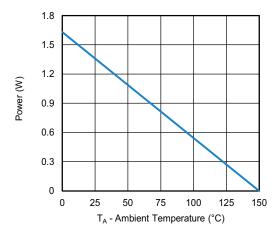




Current Derating a





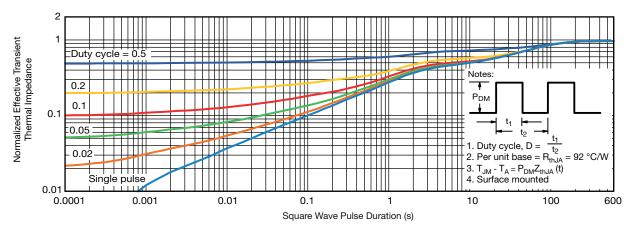


Power, Junction-to-Ambient

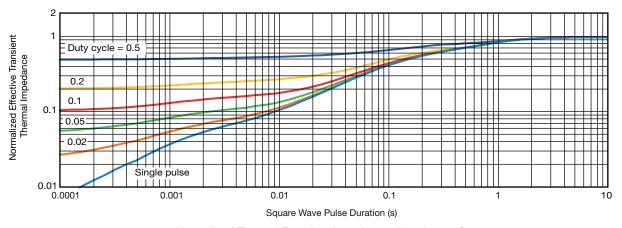
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





Normalized Thermal Transient Impedance, Junction-to-Ambient



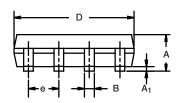
Normalized Thermal Transient Impedance, Junction-to-Case

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIM	IETERS	INCHES			
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
FCN: C-06527-Bey 11-Sen-06						

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498

Document Number: 71192 www.vishay.com 11-Sep-06 www.vishay.com



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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